

# JHB10N60EE/JHP10N60EE

## *Product Preview*

**600V 10A FIELD-STOP TRENCH IGBT WITH DIODE**

## Features

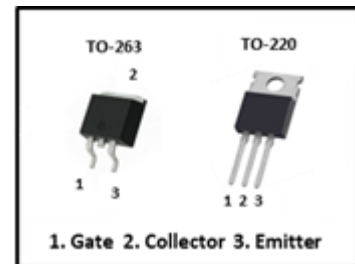
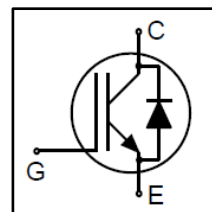
- Low  $V_{CE(sat)}$
- Fast Switching
- High Ruggedness
- Short-Circuit Rated



Product Summary	
$V_{CES}$	600V
$I_C$	10A <sup>(1)</sup>
$V_{CE(sat),typ.}$	1.45V ( $T_J = 25^\circ\text{C}$ )
Package	JHB10N60EE: TO-263 JHP10N60EE: TO-220

## Applications

- Motor Control
- Servo
- Home Appliances
- General Purpose Inverters



## Ordering Information

Part Number	Marking	Package	Packing
JHB10N60EE	HB10N60EE	TO-263	Tube
JHB10N60EE_R	HB10N60EE	TO-263	Tape and reel
JHP10N60EE	HP10N60EE	TO-220	Tube

## Absolute Maximum Ratings

Parameter	Symbol	Limit	Unit
Collector-to-Emitter Voltage	$V_{CES}$	600	V
Gate-to-Emitter Voltage	$V_{GES}$	$\pm 20$	
DC Collector Current ( $T_c = 100^\circ\text{C}, T_J = 150^\circ\text{C}$ )	$I_C$	13.7	A
Pulsed Collector Current (pulse width limited by max $T_J$ )	$I_{CM}$	40	
Diode Forward Current ( $T_c = 100^\circ\text{C}, T_J = 150^\circ\text{C}$ )	$I_F$	20	
Diode Pulsed Current (pulse width limited by max $T_J$ )	$I_{FM}$	40	
Maximum Power Dissipation ( $T_c = 25^\circ\text{C}, T_J = 150^\circ\text{C}$ )	$P_{D(max)}$	83	W
Operating Junction Temperature	$T_J$	-40 to +150	$^\circ\text{C}$
Storage Temperature	$T_{stg}$	-40 to +150	

**Static Electrical Characteristics <sup>(2)</sup>**

Parameter	Symbol	Test Conditions	Min	Typ.	Max	Unit
Collector-to-Emitter Breakdown Voltage	$BV_{CES}$	$V_{GE} = 0V, I_C = 250\mu A$	600	-	-	V
Collector-to-Emitter Leakage Current	$I_{CES}$	$V_{CE} = 600V, V_{GE} = 0V$	-	-	10	$\mu A$
		$V_{CE} = 600V, V_{GE} = 0V$ $T_J = 150^\circ C$	-	-	250	
Gate-to-Emitter Leakage Current	$I_{GES}$	$V_{CE} = 0V, V_{GE} = \pm 20V$	-	-	100	nA
Gate Threshold Voltage	$V_{GE(th)}$	$V_{CE} = V_{GE}, I_C = 250\mu A$	5.2	6.2	7.2	V
Collector-to-Emitter Saturation Voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 10A$	-	1.45	1.8	V
		$V_{GE} = 15V, I_C = 10A,$ $T_J = 150^\circ C$	-	1.7	-	
Diode Forward Voltage	$V_F$	$V_{GE} = 0V, I_F = 10A$	-	1.5	2.0	V
		$V_{GE} = 0V, I_F = 10A$ $T_J = 150^\circ C$	-	1.2	-	

**Thermal Characteristics**

Parameter	Symbol	Min	Typ	Max	Unit
Junction-to-Ambient Thermal Resistance (TO-263, TO-220)	$R_{\theta JA}$	-	-	62	$^\circ C/W$
Junction-to-Case Thermal Resistance (TO-263, TO-220), IGBT	$R_{\theta JC}$	-	-	1.5	
Junction-to-Case Thermal Resistance (TO-263, TO-220), Diode		-	-	1.4	

**Dynamic Electrical Characteristics <sup>(2)</sup>**

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Total Gate Charge	$Q_g$	$V_{CC} = 400V,$ $V_{GE} = 15V,$ $I_C = 10A$	-	21	-	nC
Input Capacitance	$C_{iss}$	$V_{CE} = 25V,$ $V_{GE} = 0V,$ $f = 1MHz$	-	570	-	pF
Output Capacitance	$C_{oss}$		-	56	-	
Reverse Transfer Capacitance	$C_{rss}$		-	12	-	

**Switching Characteristics, Inductive Load** <sup>(2), (3)</sup>

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Turn-on delay time	$t_{d(ON)}$	$V_{CC} = 400V,$ $V_{GE} = 0/15V,$ $R_G = 10\Omega,$ $I_C = 10A,$ $L_{load} = 0.82mH$ (Energy losses include "tail" and FRD reverse recovery)	-	15	-	ns
Rise Time	$t_r$		-	13	-	
Turn-off delay time	$t_{d(OFF)}$		-	70	-	
Fall Time	$t_f$		-	95	-	
Turn-On Switching Loss	$E_{on}$	(Energy losses include "tail" and FRD reverse recovery)	-	0.17	-	mJ
Turn-Off Switching Loss	$E_{off}$		-	0.16	-	
Total Switching Loss	$E_{ts}$		-	0.33	-	
Short Circuit Capability	$t_{SC}$	$V_{GE} = 15V,$ $V_{CC} \leq 400V,$ $V_P \leq 600V$	5	-	-	$\mu s$
Short Circuit Collector Current	$I_{C(SC)}$		-	65	-	A

(1)  $T_c = 115^\circ C, T_j = 150^\circ C.$

(2)  $T_j = 25^\circ C$  unless otherwise specified.

(3)  $t_r$ : from 10% of  $I_C$  to 90% of  $I_C$ ;  $t_f$ : from 90% of  $I_C$  to 10% of  $I_C$ ;

$E_{on}$ : from 10% of  $V_{GE}$  to 10% of  $V_{CE}$ ;  $E_{off}$ : from 90% of  $V_{GE}$  to 10% of  $I_C$ .

Typical Electrical Characteristics

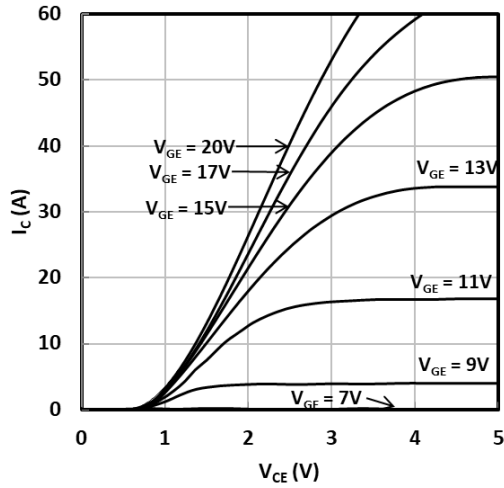


Fig. 1 Typical output characteristics

( $T_j = 25\text{ }^\circ\text{C}$ ,  $t_p = 250\text{ }\mu\text{s}$ )

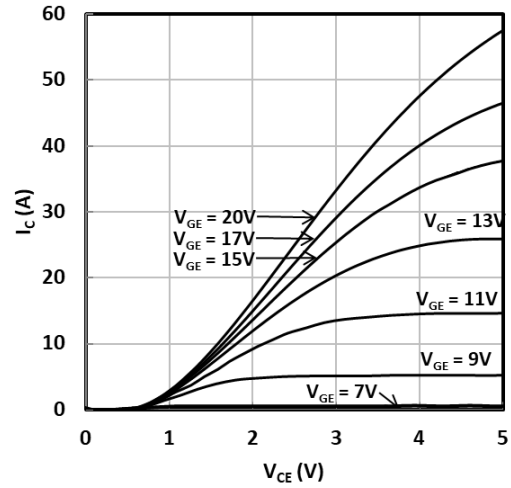


Fig. 2 Typical output characteristics

( $T_j = 150\text{ }^\circ\text{C}$ ,  $t_p = 250\text{ }\mu\text{s}$ )

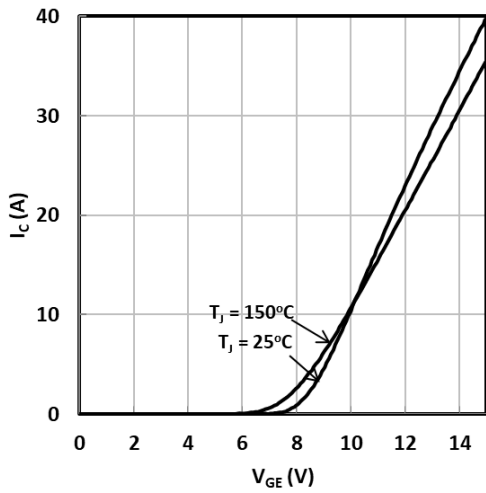


Fig. 3 Typical transfer characteristics

( $V_{ce} = 20\text{ V}$ ,  $t_p = 250\text{ }\mu\text{s}$ )

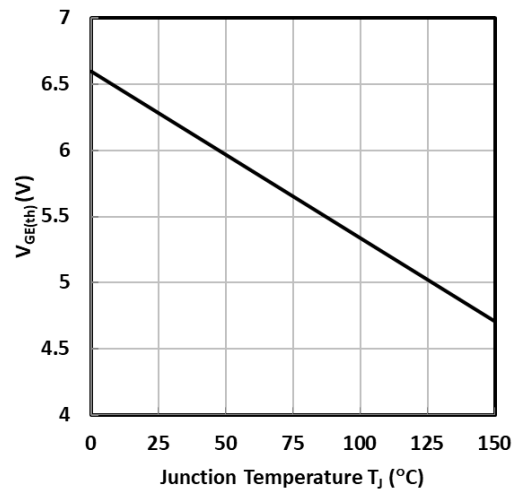
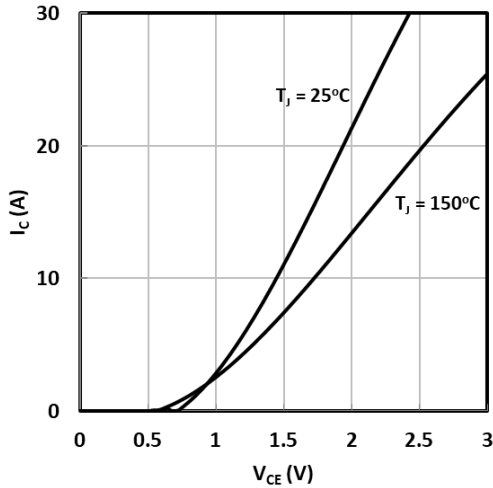
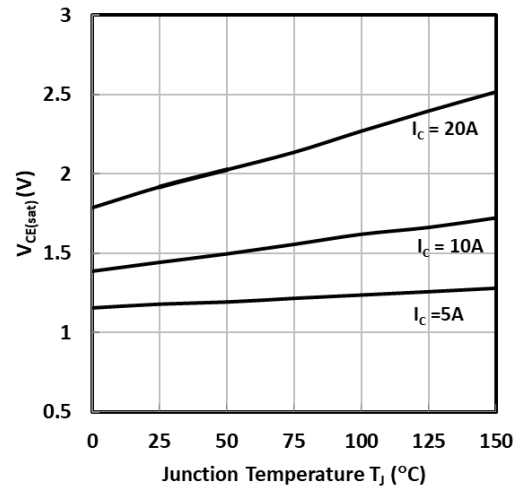


Fig. 4 Typical gate threshold voltage as a function of junction temperature

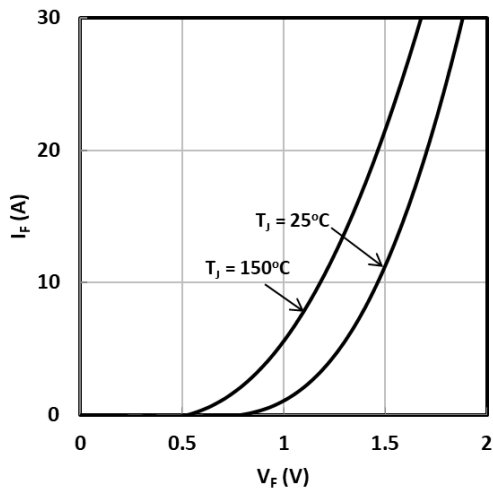
( $V_{ce} = V_{ge}$ ,  $I_c = 250\text{ }\mu\text{A}$ )



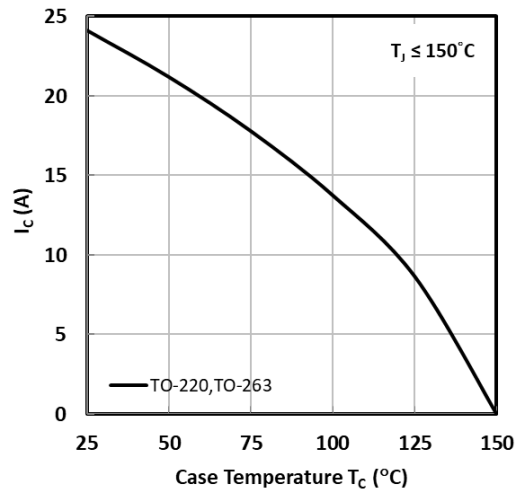
**Fig. 5 Typical saturation voltage characteristics**  
( $V_{GE} = 15\text{ V}$ ,  $t_p = 250\ \mu\text{s}$ )



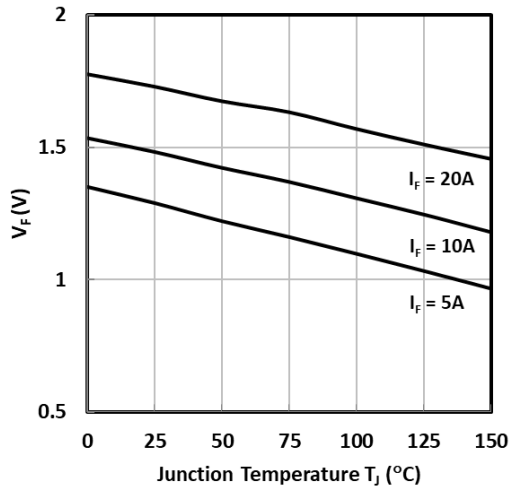
**Fig. 6 Typical saturation voltage as a function of junction temperature**  
( $V_{GE} = 15\text{ V}$ ,  $t_p = 250\ \mu\text{s}$ )



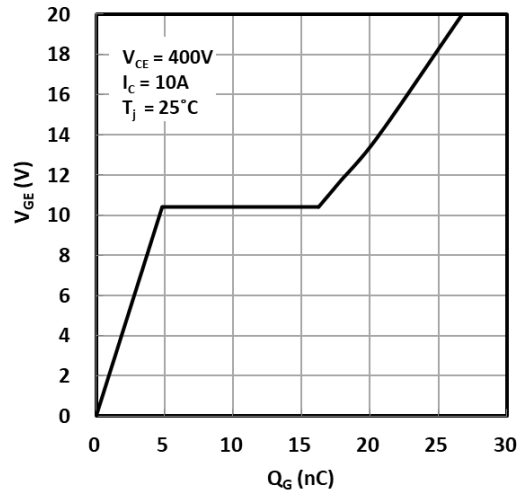
**Fig. 7 Typical diode forward current as a function of forward voltage**  
( $V_{GE} = 0\text{ V}$ ,  $t_p = 250\ \mu\text{s}$ )



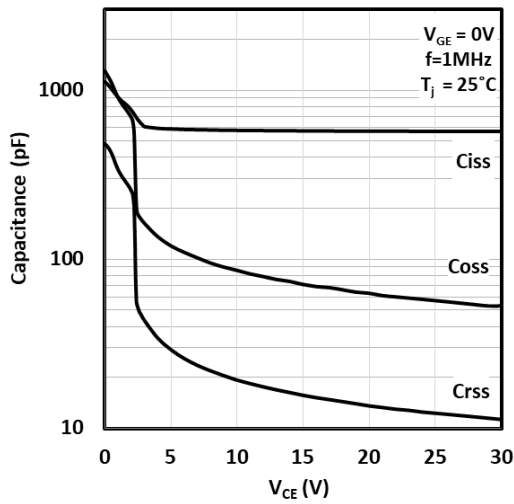
**Fig. 8 Maximum DC collector current as a function of case temperature**



**Fig. 9 Typical diode forward voltage as a function of junction temperature**  
( $V_{GE} = 0V$ ,  $t_p = 250 \mu s$ )

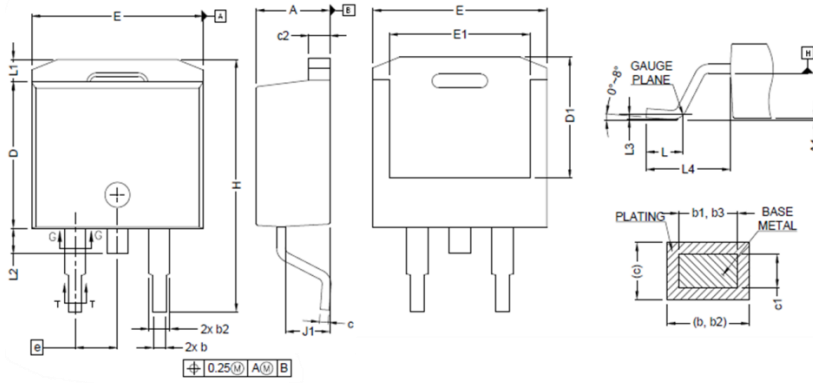


**Fig. 10 Typical gate charge characteristics**



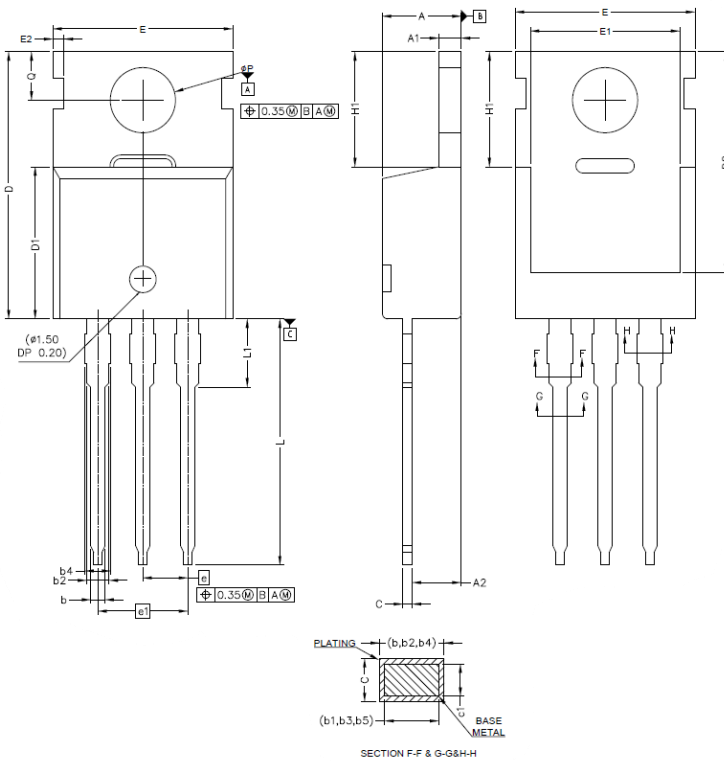
**Fig. 11 Typical capacitance as a function of collector-to-emitter voltage**

Package Drawing



SYMBOL	MIN.	MAX.
A	4.36	4.56
A1	0	0.25
b	0.70	0.90
b1	0.51	0.89
b2	1.20	1.46
b3	1.17	1.37
c	0.38	0.694
c1	0.38	0.534
c2	1.19	1.34
D	8.60	9.00
D1	6.9	7.5
E	10.15	10.55
E1	8.1	8.7
e	2.54 BSC	
H	15.0	15.6
L	1.9	2.5
L1	-	1.65
L2	-	1.78
L3	0.25 TYP	
L4	4.78	5.28
J1	2.56	2.96

TO-263



SYMBOL	MIN.	MAX.
A	4.25	4.65
A1	1.20	1.34
A2	2.56	2.92
b	0.71	0.97
b1	0.38	0.91
b2	1.14	1.78
b3	1.14	1.73
b4	1.14	1.78
b5	1.14	1.73
c	0.46	0.61
c1	0.36	0.56
D	14.32	15.86
D1	8.39	8.79
D2	12.20	12.80
E	9.96	10.36
E1	8.14	8.74
E2	0.59	0.69
e	2.54 BSC	
e1	5.08 BSC	
H1	6.30	6.70
L	13.40	14.40
L1	3.65	4.05
ØP	3.60	3.80
Q	2.54	2.94

TO-220



**Revision history of JHB10N60EE/JHP10N60EE Specification**

<b>Version</b>	<b>Change Items</b>	<b>Effective Date</b>
1.00	Initial Release.	22-Jun-20
1.01	Thermal specification updates.	24-Jun-20

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